Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form				Form Type Distribute									
Supplier	Information													
Company	name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
onsemi											2024-04-24			
Contact Na	ame	Title - Contac	Title - Contact			Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -				Citle - Representative			Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	Version	Manufacturing Site	Manufacturing Site		UOM	Unit Type	
	LC717A		.00AR-NH	OAR-NH TOUCH SENSOR 8CH 8OUT			2024-04-24		PHM	РНМ		mg	Each	
Manufacturing Process Information														
	Terminal Plating / Grid Array Material Te			Cerminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperature Max Time at Pe		eak Temper	ak Temperature Number of Reflow Cycles				
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	3			260 C 30		seconds 3					
Comments														
ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)														
For more i	For more information regarding material composition please refer to page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, so of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the restriction in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.44	mg	Supplier	Silicon (Si)	7440-21-3		1.4308	mg
			Supplier	Polyimide	Proprietary Data		0.0092	mg
Die Attach	0.06	mg	Supplier	Epoxy resins	129915-35-1		0.0435	mg
			Supplier	Acrylic resins	Proprietary Data		0.0165	mg
Mold Compound-Black	13.87	mg		Epoxy Phenol Resin	proprietary data		1.5257	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.7618	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5548	mg
Substrate and Solder Mask	4.4		В	Nickel (Ni)	7440-02-0		0.3164	mg
			Supplier	Gold (Au)	7440-57-5		0.0682	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		2.6893	mg
			Supplier	Copper (Cu)	7440-50-8		1.3262	mg
Wire Bond - Au	0.23	mg	Supplier	Gold (Au)	7440-57-5		0.23	mg